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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.
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EXAMINER

FOSTER, D

ART UNIT	PAPER NUMBER
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2841

DATE MAILED: 09/14/00

Please find below and/or attached an Office communication concerning this application or proceeding.

Commissioner of Patents and Trademarks

Office Action Summary

Application No.
09/115,444

Applicant(s)

Chen et al.

Examiner

David Foster

Group Art Unit

2841



☒ Responsive to communication(s) filed on Jul 14, 1998

☐ This action is **FINAL**.

☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11; 453 O.G. 213.

A shortened statutory period for response to this action is set to expire 3 month(s), or thirty days, whichever is longer, from the mailing date of this communication. Failure to respond within the period for response will cause the application to become abandoned. (35 U.S.C. § 133). Extensions of time may be obtained under the provisions of 37 CFR 1.136(a).

Disposition of Claims

☒ Claim(s) 1-20 is/are pending in the application.

Of the above, claim(s) _____ is/are withdrawn from consideration.

☐ Claim(s) _____ is/are allowed.

☒ Claim(s) 1-20 is/are rejected.

☐ Claim(s) _____ is/are objected to.

☐ Claims _____ are subject to restriction or election requirement.

Application Papers

☐ See the attached Notice of Draftsperson's Patent Drawing Review, PTO-948.

☒ The drawing(s) filed on Jul 14, 1998 is/are objected to by the Examiner.

☐ The proposed drawing correction, filed on _____ is ☐ approved ☐ disapproved.

☐ The specification is objected to by the Examiner.

☐ The oath or declaration is objected to by the Examiner.

Priority under 35 U.S.C. § 119

☐ Acknowledgement is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d).

☐ All ☐ Some* ☐ None of the CERTIFIED copies of the priority documents have been
☐ received.

☐ received in Application No. (Series Code/Serial Number) _____.

☐ received in this national stage application from the International Bureau (PCT Rule 17.2(a)).

*Certified copies not received: _____

☐ Acknowledgement is made of a claim for domestic priority under 35 U.S.C. § 119(e).

Attachment(s)

☒ Notice of References Cited, PTO-892

☒ Information Disclosure Statement(s), PTO-1449, Paper No(s). 5

☐ Interview Summary, PTO-413

☐ Notice of Draftsperson's Patent Drawing Review, PTO-948

☐ Notice of Informal Patent Application, PTO-152

--- SEE OFFICE ACTION ON THE FOLLOWING PAGES ---

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DETAILED ACTION

HIGH DENSITY INTERNAL BALL GRID ARRAY INTEGRATED CIRCUIT

PACKAGE

Chen et al.

Drawings

1. The drawings are objected to because Figure 2 shows printed circuit board (70) with line drawn to only top portion of the mounting structure. The printed circuit board is the combination of the top and the bottom wherein the bottom is the mounting for the silicon chip.

Correction is required.

Claim Rejections - 35 USC § 112

2. The following is a quotation of the second paragraph of 35 U.S.C. 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

3. Claim 2 is rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.
4. Claim 2 recites the limitation "said substrate has a first and second layer" in line 12, page

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29. There is insufficient antecedent basis for this limitation in the claim. Rather, the specification, page 20, line 10 describes "Figure 2 depicts printed circuit board 70 as having two layers, top layer 76 and bottom layer 78, it should be understood by one skilled in the art that printed circuit board 70 may consist of a single layer or may be a multilayered board". Applicant must modify either the specification or claim 2 acknowledging that the is printed circuit board is multilayer or it is a single layer.

5. The term "high density ball grid array" in claim 6 is a relative term which renders the claim indefinite. The term "high density ball grid array" is not defined by the claim, the specification does not provide a standard for ascertaining the requisite degree, and one of ordinary skill in the art would not be reasonably apprised of the scope of the invention. The term high density ball grid array does not define the metes and bounds necessary to ascribe whether the ball grid array is high density or low density..

Claim Rejections - 35 USC § 103

6. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

7. Claims 1-20 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yamaguchi (5,886,876).

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Reference claim 1 and 8. Yamaguchi discloses an integrated circuit package comprising: a substrate (Figure 2, item 11) having a plurality of peripheral openings (Figure 1, items 19) and first and second surfaces (Figure 2c); a chip adhered to said second surface of said substrate (Figure 2c, item 13); a plurality of pads disposed on said first surface of said substrate generally centralized within said peripheral openings of said substrate (Figure 2, items 14); and potting material filling said peripheral openings (Figure 6, item 25 and column 6, line 58) and wire bonding electrically connecting said chip to said substrate between said bonding pads and said routing strips (Figure 2c, item 21 and column 4, line 36).

Reference claim 3. Yamaguchi discloses an integrated circuit package as recited in claim 1 further comprising a plurality of routing strips being integral with said substrate (Figure 2, items 14).

Reference claim 4. Yamaguchi discloses an integrated circuit package as recited in claim 3 wherein at least one of said pads disposed on said first surface of said substrate is electrically connected with at least one of said routing strips (Figure 2c, item 21).

Reference claim 5. Yamaguchi discloses an integrated circuit package as recited in claim 1 further comprising at least one solder ball disposed on one of said pads (Figure 2c, items 18).

Reference claim 6. Yamaguchi discloses an integrated circuit package as recited in claim 1 further comprising a plurality of solder balls (Figure 1, items 18) disposed on said pads forming a high density ball grid array.

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Reference claim 7. Yamaguchi discloses an integrated circuit package as recited in claim 1 wherein said potting material adheres said chip to said substrate (Figure 2c and column 5, line 35).

Reference claim 9. Yamaguchi discloses an integrated circuit package as recited in claim 8 further comprising at least one solder ball disposed on one of said pads (Figure 1, item 18).

Reference claim 10. Yamaguchi does not disclose an integrated circuit package as recited in claim 9 wherein said at least one solder ball is between about 8 and 20 mils in diameter. However, even though Yamaguchi does not disclose the diameter of the solder balls, the scope of the Yamaguchi package is similar and the Yamaguchi package could, indeed, include solder balls which range in size from 8 to 20 mils in diameter.

Reference claim 11. Yamaguchi discloses an integrated circuit package as recited in claim 8 further comprising a plurality of solder balls disposed on said pads forming a high density ball grid array (Figure 2c, items 18).

Reference claim 12. Yamaguchi does not disclose an integrated circuit package as recited in claim, to 8 wherein said chip has a thickness between about 10 and 20 mils. However, even though Yamaguchi does not disclose the thickness of the chip, the scope of the Yamaguchi package is similar and the Yamaguchi package could, indeed, include chips which range in size from 10 to 20 mils in thickness.

Reference claim 13, 14 and 15. Yamaguchi does not disclose an integrated circuit package as recited in claim 8 wherein said substrates have a thicknesses of between about 8 and 28 mils. However, even though Yamaguchi does not disclose the thickness of the substrate, the scope of

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the Yamaguchi package is similar and the Yamaguchi package could, indeed, include a substrate which ranges in thickness from 8 to 28 mils in thickness.

Reference claim 16. Yamaguchi discloses an integrated circuit package comprising: a substrate having a plurality of peripheral openings (Figure 1, items 19), first and second surfaces (Figure 2c) and an outline; a plurality of routing strips being integral with said substrate (Figure 2c, items 14); a plurality of pads centrally disposed on said first surface at least one of said pads being electrically connected with said routing strips (Figure 2c, items 21); a chip adhered to said second surface of said substrate (Figure 2c, item 13), said chip having an outline that is substantially the same as said outline of said substrate (Figure 2a) and having a plurality of bonding pads (Figure 2a, items 14); wire bonding electrically connecting said bonding pads to said routing strips (Figure 2a, items 21); vias connecting said routing strips to said pads (Figure 2a, items 17); potting material filling said peripheral openings and covering said wire bonding and said bonding pads (Figure 6, item 25 and column 6, line 58); and a plurality of solder balls centrally disposed on said pads disposed on said first surface of said substrate forming a high density ball grid array (Figure 2c, items 18).

Reference claim 17, 18, 19 and 20. Yamaguchi does not disclose an integrated circuit package as recited in claim 16 wherein said chip has a thickness between about 10 and 20 mils, said substrate has a thickness of between about 8 and 28 mils, said substrate has first and second layers and therein said first layer has a thickness of about 12 mils and said second layer has a thickness of about 8 mils and said substrate has first, second and third layers and wherein said first layer has a

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thickness of about 12 mils. However, even though Yamaguchi does not disclose the chip thickness, thickness of the substrate, the scope of the Yamaguchi package is similar and the Yamaguchi package could, indeed, include a substrate which ranges in thickness from 8 to 28 mils in thickness.

Conclusion

8. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. The best art to consider with this application can be found in: Marcantonio (5,796,170), Takamichi et al. (6,054,755), Ha et al. (5,767,446), Chia et al. (5,973,393), Selna (5,640,048), Gaudenzi et al. (5,313,366), Hoppe (4,843,225). Marcantonio discloses BGA integrated circuit having a vent hole, substrate, pads and ball grid array, Takamichi et al. disclose a semiconductor package with moisture vapor relief wherein moisture vapor in the package is released outside through the vent hole, Ha et al. disclose a semiconductor package having a substrate, chip, ball grid and a molded seal, Chia et al. disclose an apparatus and method for packaging and IC, Selna discloses a three-layer BGA package having vias, Gaudenzi et al. disclose a surface mount carrier, pads, a chip and solder balls and Hoppe discloses an identification card with and IC wherein polymer is injected in the cavity.

9. Any inquiry concerning to this communication or earlier communications from the Examiner should be directed to David Foster whose telephone number is (703) 308-1763. The examiner can normally be reached on Monday through Thursday and alternate Fridays.

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If attempts to reach the Examiner by telephone are unsuccessful, the Examiner's Supervisor, Jeffrey A. Gaffin, who can be reached on (703) 308-3301. The fax phone number for the organization where this application or proceeding is assigned is (703)308-7724.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.



DAVID FOSTER

DAF

September 12, 2000